

December 2014

## FCU4300N80Z

# N-Channel SuperFET® II MOSFET

**800 V, 1.6 A, 4.3** Ω

### **Features**

- $R_{DS(on)} = 3.4 \Omega (Typ.)$
- Ultra Low Gate Charge (Typ. Q<sub>q</sub> = 6.8 nC)
- Low E<sub>oss</sub> (Typ. 0.8 uJ @ 400V)
- Low Effective Output Capacitance (Typ. C<sub>oss(eff.)</sub> = 36 pF)
- · 100% Avalanche Tested
- · RoHS Compliant
- · ESD Improved Capability

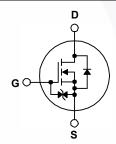
## **Applications**

- · AC DC Power Supply
- · LED Lighting

## **Description**

SuperFET® II MOSFET is Fairchild Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. In addition, internal gate-source ESD diode allows to withstand over 2kV HBM surge stress. Consequently, SuperFET II MOSFET is very suitable for the switching power applications such as Audio, Laptop adapter, Lighting, ATX power and industrial power applications.





### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol		Parameter		FCU4300N80Z	Unit
V <sub>DSS</sub>	Drain to Source Voltage			800	V
V		- DC	/	±20	V
$V_{GSS}$	Gate to Source Voltage	- AC	(f > 1 Hz)	±30	V
I <sub>D</sub> Drain Current		- Continuous (T <sub>C</sub> = 25°C)		1.6	Α
		- Continuous (T <sub>C</sub> = 100°C)		1.0	_ A
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	3.2	Α
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)			8.2	mJ
I <sub>AR</sub>	Avalanche Current (Note 1)			0.32	Α
E <sub>AR</sub>	Repetitive Avalanche Energy	Repetitive Avalanche Energy (Note 1)			mJ
dv/dt	MOSFET dv/dt			100	1//20
dv/dt	Peak Diode Recovery dv/dt	Peak Diode Recovery dv/dt (Note 3)			V/ns
D	Davies Dissination	$(T_C = 25^{\circ}C)$		27.8	W
$P_{D}$	Power Dissipation  - Derate Above 25°C			0.22	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range			-55 to +150	οС
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds			300	οС

### **Thermal Characteristics**

Symbol	Parameter FCU4300N80Z			
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	4.5	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	100	- C/VV	

## **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCU4300N80Z	FCU430080Z	IPAK	Tube	N/A	N/A	75 units

## **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	lest Conditions	Wiin.	ıyp.	wax.	Unit
Off Chara	cteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 25^{\circ}\text{C}$	800	-	-	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 1 mA, Referenced to 25°C	-	0.85	-	V/°C
I	Zero Gate Voltage Drain Current	$V_{DS} = 800 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	25	μА
IDSS	Zero Gate voltage Drain Current	$V_{DS} = 640 \text{ V}, V_{GS} = 0 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	250	μΑ
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±10	μΑ

### **On Characteristics**

V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}$ , $I_{D} = 0.16$ mA	2.5	-	4.5	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 0.8 \text{ A}$	-	3.4	4.3	Ω
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 20 \text{ V}, I_{D} = 0.8 \text{ A}$	-	0.52	-	S

## **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	400 4 4 4 0 4	-\	267	355	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, f = 1 MHz	- \	12	16	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 WI 12	-	0.78	-	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	6.2	-	pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	$V_{DS} = 0 \text{ V to } 480 \text{ V}, V_{GS} = 0 \text{ V}$	-	36	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10V	V <sub>DS</sub> = 640 V, I <sub>D</sub> = 1.6 A,	-	6.8	8.8	nC
$Q_{gs}$	Gate to Source Gate Charge	V <sub>GS</sub> = 10 V	-	1.38	-	nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge	(Note 4)	-	3.0	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	2.9	-	Ω

### **Switching Characteristics**

	_						
t <sub>d(on)</sub>	Turn-On Delay Time			-	10	30	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 400 \text{ V}, I_D = 1.6 \text{ A},$		-	6.5	23	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS}$ = 10 V, $R_g$ = 4.7 $\Omega$		- /	21	52	ns
t <sub>f</sub>	Turn-Off Fall Time		(Note 4)	-	16	42	ns

### **Drain-Source Diode Characteristics**

Is	Maximum Continuous Drain to Source Diode Forward Current	-	-	1.6	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current	-	-	3.2	Α
$V_{SD}$	Drain to Source Diode Forward Voltage V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 1.6 A		-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time $V_{GS} = 0 \text{ V}, I_{SD} = 1.6 \text{ A},$	-	209	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge dI <sub>F</sub> /dt = 100 A/μs		1.2	-//	μС

#### Notes:

- 1. Repetitive rating: pulse width limited by maximum junction temperature.
- 2. I $_{AS}$  = 0.32 A, R $_{G}$  = 25  $\Omega$ , starting T $_{J}$  = 25°C
- 3. I  $_{SD} \leq$  1.6 A, di/dt  $\leq$  200 A/µs, V  $_{DD} \leq$  BV  $_{DSS}$  , starting T  $_{J}$  = 25°C
- 4. Essentially independent of operating temperature typical characteristic.

## **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

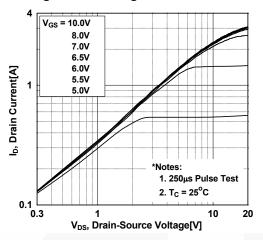


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

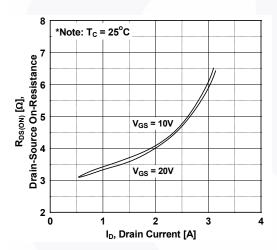


Figure 5. Capacitance Characteristics

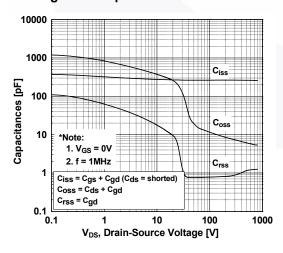


Figure 2. Transfer Characteristics

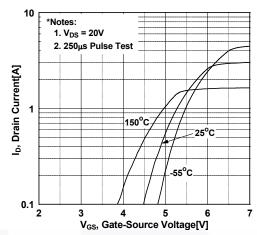
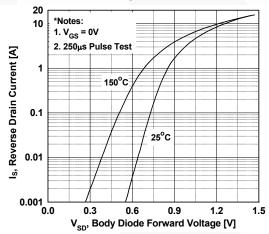
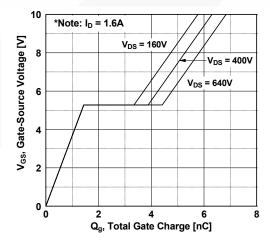


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature



**Figure 6. Gate Charge Characteristics** 



## **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

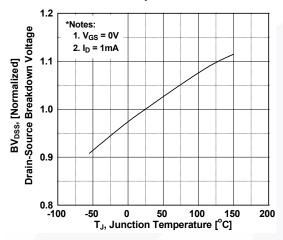


Figure 9. Maximum Safe Operating Area

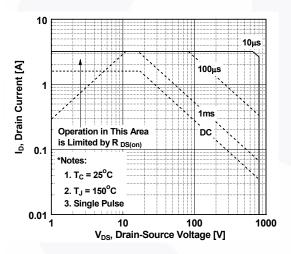


Figure 11. Eoss vs. Drain to Source Voltage

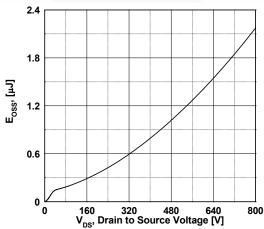


Figure 8. On-Resistance Variation vs. Temperature

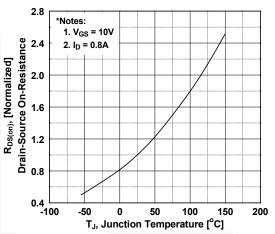
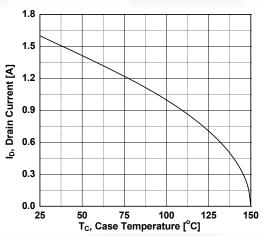
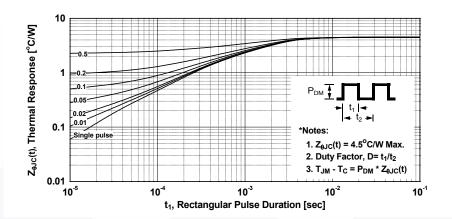


Figure 10. Maximum Drain Current vs. Case Temperature



## **Typical Performance Characteristics** (Continued)

**Figure 12. Transient Thermal Response Curve** 



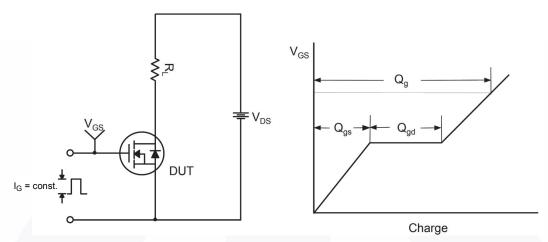


Figure 13. Gate Charge Test Circuit & Waveform



Figure 14. Resistive Switching Test Circuit & Waveforms

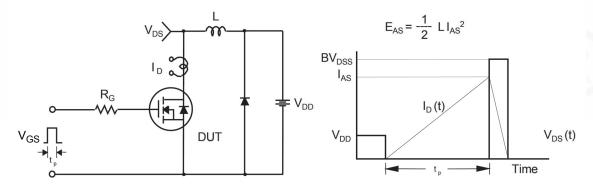


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

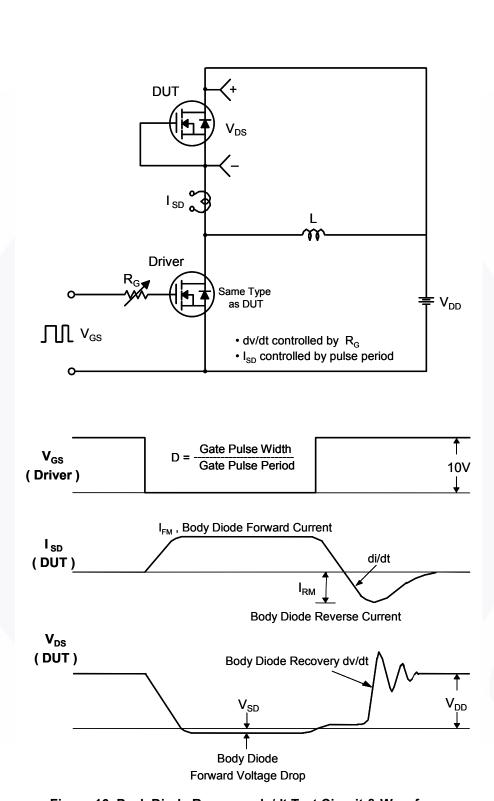
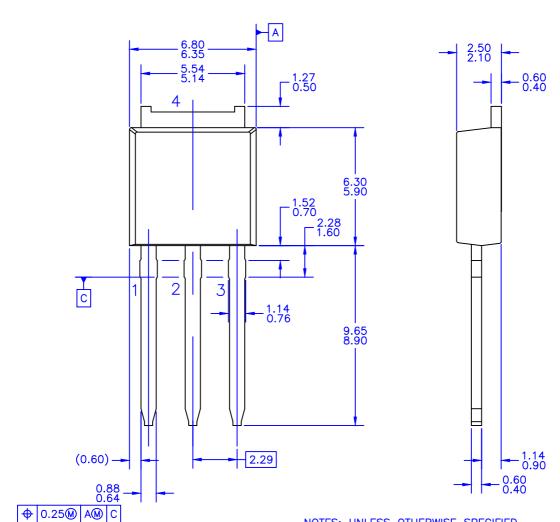
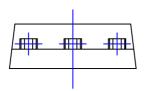


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms





3 PLCS

NOTES: UNLESS OTHERWISE SPECIFIED

- ALL DIMENSIONS ARE IN MILLIMETERS.
- B) THIS PACKAGE CONFORMS TO JEDEC, TO-251, ISSUE C, VARIATION AA, DATED SEP 1988.
  C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- DRAWING NUMBER AND REVISION: MKT-T0251A03REV2 D)







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